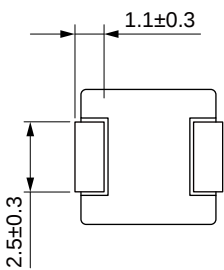
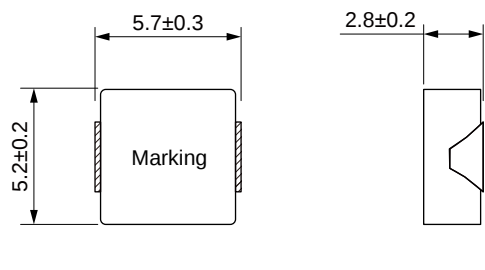


MDA Series
SMD Low Profile High Current Molded Inductor
Size 5030

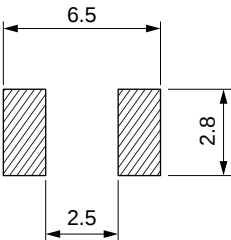
FEATURES

- Shielded construction
- Capable of corresponding high frequency .
- Low loss realized with low DCR.
- High performance (Isat) realized by metal dust core.
-
-
-
-
-

Dimensions: [mm]



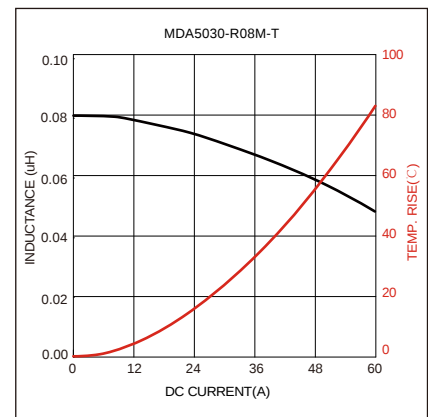
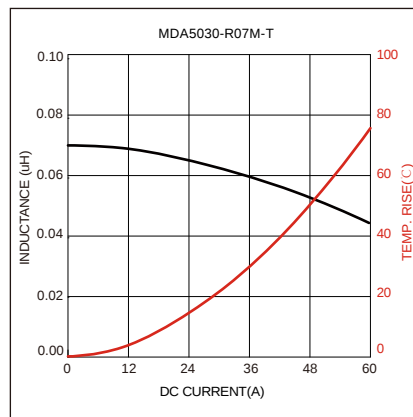
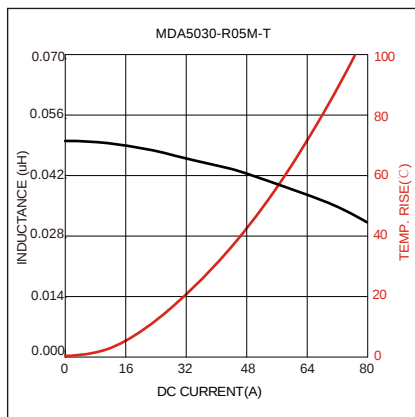
Land Pattern: [mm]



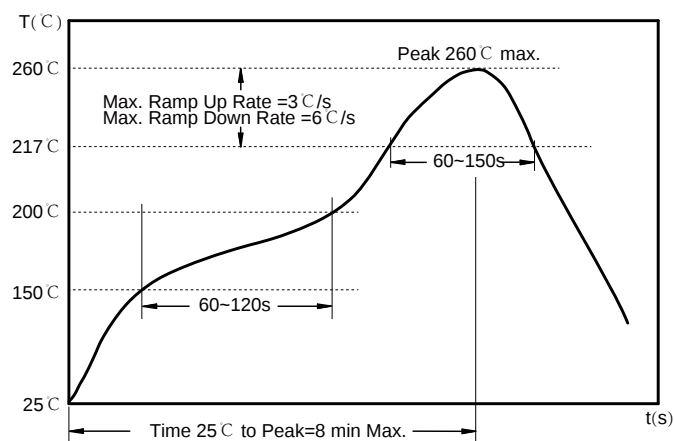
Electrical Properties:

	(μ H)			Satura on	(m Ω)	(m Ω)
MDA5030-R05M-T	0.05	$\pm 20\%$	46	68	0.57	0.63
MDA5030-R07M-T	0.07	$\pm 20\%$	42	52	0.64	0.71
MDA5030-R08M-T	0.08	$\pm 20\%$	40	50	0.74	0.85

Typical Electrical Characteristics:



Soldering Reflow:



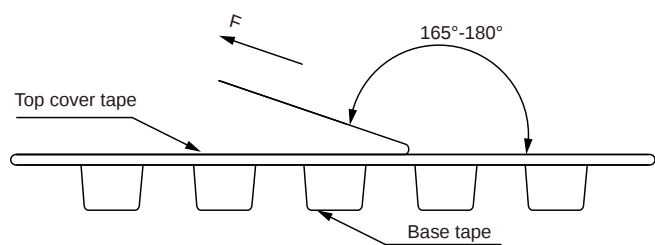
Preheat condition: 150 ~200℃ / 60~120 sec.
Allowed time above 217℃ : 60~150 sec.
Max temperature: 260℃ .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA5030-T	5.5 ± 0.1	6.2 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	8.0 ± 0.1	12.0 ± 0.3	3.3 ± 0.1	1.75 ± 0.1	0.35 ± 0.05

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	Printing Inductance+period)
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Reel Dimension: [mm]

Packaging Quantity: